



2026 IEEE 18th International Conference on Solid-State and Integrated Circuit Technology (ICSICT)

Oct. 27 - 30, 2026 Hangzhou, China

Conference Website: www.icsict.org

ICSICT 2026 ABOUT CONFERENCE

2026 IEEE 18th International Conference on Solid-State and Integrated Circuit Technology (ICSICT) in the series aiming to provide an international forum for the presentation and discussion of recent advances in solid-state and integrated circuit technology. The conference will be held on Oct. 27 - 30, 2026 in Hangzhou, China. All aspects of solid-state devices, circuits and systems, process technologies, materials and other related research are within the scope of the conference. Over the course of four days, a rich program of contributed and invited presentations will cover the latest advancements in various fields. These presentations will be delivered through both oral and poster sessions, accompanied by panel discussions addressing cutting-edge technology issues and various engaging activities. This comprehensive program aims to foster extensive opportunities for the exchange of technical information and create a stimulating atmosphere for mutual communication among all participants. The presentation of the Excellent Student Paper Award and the Outstanding Young Scholar Paper Award will take place during the conference's closing ceremony. Enterprises with relevance to the event are encouraged to join and actively take part in the exhibition.

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ICSICT 2026 KEYNOTE SPEAKERS



Jianjun Luo
Hangzhou Dianzi University, China



Mohamad Sawan
Westlake University, China



Wai Tung Ng
University of Toronto, Canada



Zewen Liu
Tsinghua University, China

ICSICT 2026 CONFERENCE SCOPE

Paper submissions are solicited in, but not limited to the following areas:

- Theme 1: Digital & System Level IC**
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- Track 1: Digital Architectures & Systems**
Chair: Zhiyi Yu, Sun Yat-sen University, China
Co-Chairs: Yaoyu Tao, Peking University, China
Hongyang Jia, Tsinghua University, China
- Track 2: Digital Circuits**
Chair: Yongpan Liu, Tsinghua University, China
Co-Chairs: Yanan Sun, Shanghai Jiao Tong University, China
Fengbin Tu, Hong Kong University of Science and Technology, China
- Track 3: Design Methodology & EDA**
Chair: Jun Yang, Southeast University, China
Co-Chairs: Yibo Lin, Peking University, China
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- Theme 2: Analog**
Chair: Jing Jin, Shanghai Jiao Tong University, China
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- Track 4: RF & Wireless**
Chair: Keping Wang, Tianjin University, China
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- Track 5: Wireline**
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- Track 6: General Analog**
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- Theme 3: Devices**
Chair: Wentong Zhang, University of Electronic Science and Technology of China, China
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- Track 7: CMOS Logic Devices & Sensors**
Chair: Heng Wu, Peking University, China
Co-Chairs: Wang Kang, Beihang University, China
Xiaosheng Zhang, University of Electronic Science and Technology of China, China
- Track 8: Power Devices & Power IC**
Chair: Long Zhang, Southeast University, China
Co-Chairs: Jiafei Yao, Nanjing University of Posts and Telecommunications, China
Zekun Zhou, University of Electronic Science and Technology of China, China
- Track 9: Device Reliability & Security**
Chair: Mengyuan Hua, Southern University of Science and Technology, China
Co-Chairs: Sen Huang, Institute of Microelectronics of Chinese Academy of Sciences, China
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- Theme 4: Process & Technologies**
Chair: Haifeng Ling, Nanjing University of Posts and Telecommunications, China
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- Track 10: Semiconductor Process Technologies**
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- Track 11: Optoelectronics and Silicon Photonics Integration**
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- Track 12: Packaging Technologies**
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Co-Chairs: Shenyang Mo, NARI Semiconductor R&D Center, China
Pengfei Zhao, Nanjing University of Posts and Telecommunications, China

ICSICT 2026 PAPER SUBMISSION

Prospective authors are requested to submit at least 3 pages camera-ready full length paper in English. Accepted papers will be included in conference proceedings.

Submission System



The submission system for ICSICT 2026 has been opened. Welcome to submit papers through:
<https://easychair.org/conferences/?conf=icsict2026>

Important Dates

Deadline for Paper Submission	June 25, 2026
Notification of Acceptance	July 25, 2026

* Visit the following page to view the detail submission guidelines: <https://www.icsict.org/Submission.html>